

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| 1 | 1 | reinforced adj semiconductor adj interconnect adj structure | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:38 |
| 2 | 3 | reinforced adj interconnect adj structure | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:40 |
| 3 | 15 | reinforced adj interconnect | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:41 |
| 4 | 72 | reinforced adj via | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:43 |
| 5 | 56 | reinforced adj plug | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:44 |
| 6 | 7 | reinforced adj semiconductor adj (device or structure or portion or element) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:45 |
| 7 | 39 | reinforced adj semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:46 |
| 8 | 638 | semiconductor adj supports | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:46 |
| 9 | 73 | semiconductor adj support adj structures | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:48 |
| 10 | 9 | semiconductor adj support adj elements | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:49 |
| 11 | 7 | semiconductor adj support adj (region or area or potion) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:49 |
| 12 | 11 | semiconductor adj support adj (region or area or portion) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 11:51 |
| 13 | 150 | (multilevel adj metallization) and (supports or reinforcements) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 12:00 |
| 14 | 56 | (plurality adj metallization) and (supports or reinforcements) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/15 12:10 |
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| 15 | 202 | (plurality adj metal adj (layers or films)) and (supports or reinforcements) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:13 |
| 16 | 45 | (first adj metal adj interconnect) and (supports or reinforcements) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:16 |
| 17 | 283 | first adj metal adj interconnect | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:21 |
| 18 | 62 | plurality adj metal adj interconnect | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:22 |
| 19 | 36 | multiple adj metal adj interconnect | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:24 |
| 20 | 87 | multilevel adj metal adj interconnect | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/11/15 12:24 |